Tool Configuration / Specifications

SYSTEM SPECIFICATIONS:
Wafer Handling
Manual with loading paddle to center wafer
Solvent Dispense
Pressurized tank required
Substrate Sizes (Max.)
9" round, 6" square, 9" diagonal rectangular
Tachometer
Digital readout from optical encoder
10 rpm resolution
Acceleration
Variable from 1,000 to 40,000 rpm/sec
Process Control
Digital timers with manual programming
Relay logic
Time
Variable from 1 to 999 seconds in 1 second increments
Resist Dispense
Automatic Teflon diaphragm pump with precise dispense adjustment; 0.5 to 38 mlt1%; viscosity 4 to 10,000 centistokes; separate drawback adjustment
Speed Control
Closed loop servo with t10 rpm speed control
Adjustable from 200 to 10,000 rpm
Digital reference on spin and spread speeds
Standard Process Sequence
Resist coat (static or dynamic)
Spread
Spin

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